

BCC Resins HPX-850

Epoxy; Epoxide

BCC Products Inc.

Message:

HPX-850 is a light weight, heat resistant, two component epoxy backfill system. Like BC 7020, the filler portion is pre-blended into the resin and hardener components for easier handling, thus simplifying the mixing process. HPX-850 features advantages such as low cost, long pot life, machineability, and low shrinkage. It is ideally suited for numerous applications involving mold and core constructions.

HPX-850 can be removed from the mold after allowing to set 24 hours @ room temperature (75°F). Post cure for applications requiring temperatures above 150°F can be accomplished in an oven or in use by a gradual heat rise; 2 hours @ 150°F, plus 2 hours @ 250°F, plus 2 hours at 300°F.

General Information			
Features	High Heat Resistance		
	Low Shrinkage		
	Machinable		
Uses	Molds/Dies/Tools		
Appearance	Grey		
Forms	Paste		
Processing Method	Casting		
Physical	Nominal Value	Unit	Test Method
Specific Gravity			
--	0.818	g/cm ³	ASTM D792
--	0.830	g/cm ³	ASTM D1505
Molding Shrinkage - Flow	0.020	%	ASTM D955
Thermal	Nominal Value	Unit	Test Method
Deflection Temperature Under Load (1.8 MPa, Unannealed)	141	°C	ASTM D648
Thermoset	Nominal Value	Unit	
Thermoset Components			
Hardener	Mix Ratio by Weight: 1.0		
Resin	Mix Ratio by Weight: 6.0		
Pot Life (24°C)	120 to 150	min	
Demold Time	1400	min	

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